SEMICONDUCTOR PACKAGE

ABSTRACT OF THE DISCLOSURE

A semiconductor package is disclosed that bonds a semiconductor chip to a leadframe using a flip chip technology. An exemplary semiconductor package includes a semiconductor chip having a plurality of input-output pads at an active surface thereof. A plurality of leads are superimposed by the bond pads and active surface of the semiconductor chip. The leads have at least one exposed surface at a bottom surface of the package body. A plurality of conductive connecting means electrically connect the input-output pads of the chip to the leads. A package body is formed over the semiconductor chip and the conductive connecting means. The bottom surface portions of the leads are exposed to the outside.

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